

**In the claims:**

Cancel **Claim 1.**

**Claim 2** (currently amended)      A tin-silver based lead-free solder containing 0.3 to 1% of zinc further containing 8 to 10% by weight of indium (In) ~~added thereto~~.

**Claim 3** (cancelled).

Cancel **Claim 4.**

**Claim 5** (currently amended)      A joint structure, comprising bodies to be joined are joined together by the tin-silver based lead-free solder of claim ~~1~~ 2.

**Claim 6** (previously presented)      The joint structure of claim 5, wherein an electroless plating layer is provided on surfaces of said bodies to be joined.

**Claim 7** (previously presented)      The joint structure of claim 6, wherein said-electroless-plating layer is a Ni-Pplating.

Cancel **Claim 8.**

**Claim 9** (currently amended)  
of silver.

A solder of claim 2 containing 3 to 3.5% by weight

Cancel **Claims 10 to 16.**